UNITED STATES PATENT AND TRADEMARK OFFICE **CERTIFICATE OF CORRECTION**

PATENT NO. : 6,838,391 B2

DATED

: January 4, 2005

INVENTOR(S) : Volker Harle

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page,

Item [56], References Cited, OTHER PUBLICATIONS,

"B. Henle," reference, replace "On Indium Phosphide & Rel. Materials, U.S. NY; IEEE, Bd." with -- On Idium Phosphide & Rel. Materials, U.S. NY IEEE, Bd. --J.P. Harbinson et al.," reference, replace "J.P. Harbinson et al., "Tungsten Patterning As A Technique" with -- J.P. Harbison et al., "Tungsten Patterning As A Technique --"JP 02-046407", reference, replace "JP 02-046407, Patent Abstracts of Japan, Veroffentlicung:" with -- JP 02-046407, Patent Abstracts of Japan, Veroffentlichung: --"Whidden T.K. et al." reference, replace "Whidden T.K. et al.; "Catalyzed HF Vapor Etcing Of' with -- Whidden T.K. et al.; "Catalyzed HF Vapor Etching Of --"Wong M. et al.," reference, replace "Oxide And Oxide Etching Using Vapor-Phase Hydrgoen" with -- Oxide And Oxide Etching Using Vapor-Phase Hydrogen --

Column 5,

Line 29, replace "more from a group consisting of an underlying mask layer" with -- or more from a group consisting of an underlying mask layer --Line 51, replace "defined an at least one (N+1)th semiconductor compo-" with -- defined and at least one (N+1)th semiconductor-compo---

Column 6,

Line 29, replace "any remaining mask is moved by etching." with -- any remaining mask is removed by etching. --

Signed and Sealed this

Twenty-fourth Day of May, 2005

JON W. DUDAS Director of the United States Patent and Trademark Office